



ASCENT[®] DMS
ADVANCED DUAL-MAGNETRON SPUTTERING ACCESSORIES,
30 TO 180 KW





Facilitating Process Innovation for Tomorrow's Advanced Applications

The Ascent® DMS series offers unprecedented power-delivery ease and control for dual-magnetron sputtering, enabling precise tuning of film characteristics. With selectable frequency, regulation mode, and duty cycle, as well as low stored energy and simplified, modular system configuration, the Ascent DMS accessory distinguishes itself as truly next-generation technology. Cost-effective, scalable, and versatile, it minimizes complexity, increases quality, and boosts throughput to enable advanced process innovation.

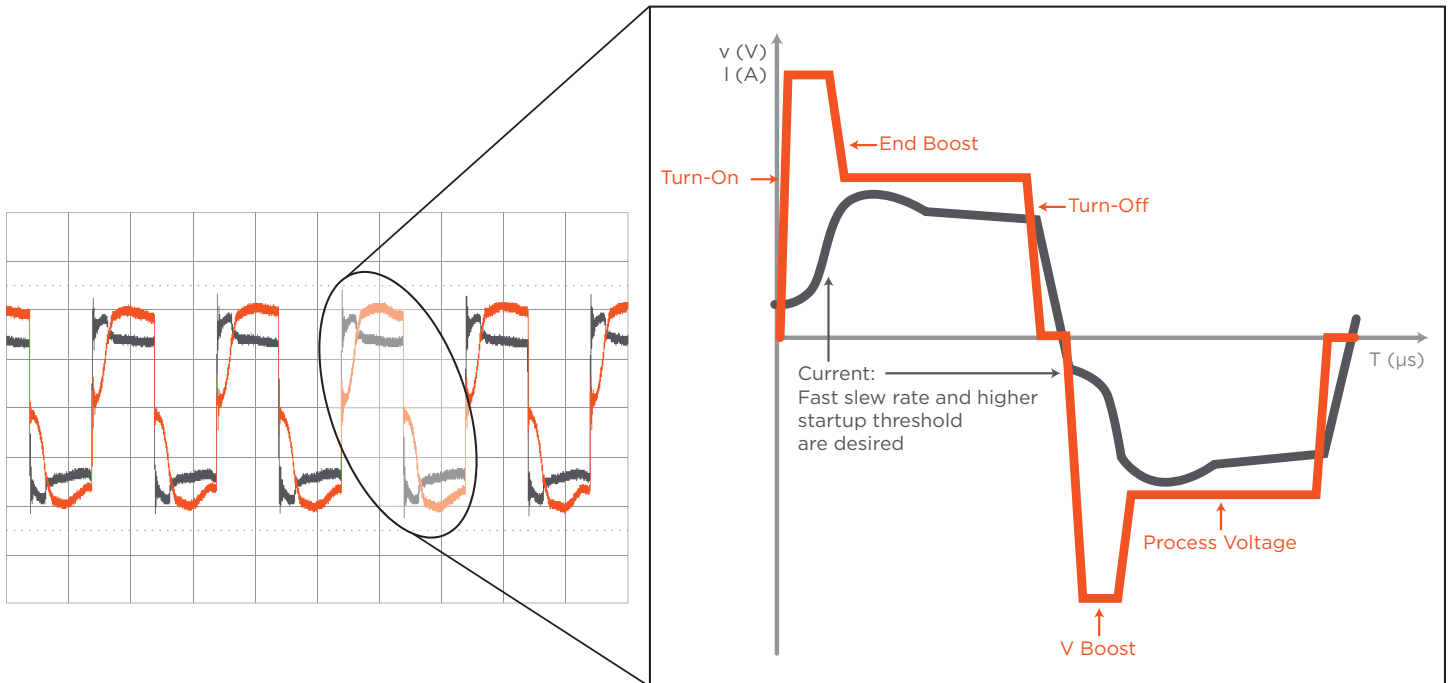
- **Increased film value: repeatable, customizable deposited films**
- **Lower cost of ownership and increased productivity**
- **Lower upfront costs**
- **Higher power levels with reduced arc damage**
- **Easy scalability, integration, and support**

FEATURES

- MODULAR AND SCALABLE (30, 40, AND 60 KW UNITS CONFIGURABLE UP TO 180 KW)
- SELECTABLE FREQUENCY (500 HZ TO 50 KHZ)
- POWER, CURRENT, OR VOLTAGE REGULATION
- ADJUSTABLE DUTY CYCLE—INDEPENDENT POWER RATIO REGULATION FOR EACH MAGNETRON
- UNIPOLAR AND BIPOLAR OPERATION
- LOWEST ARC ENERGY POSSIBLE FROM ANY INDUSTRIAL DUAL-MAGNETRON SPUTTERING SUPPLY
- CEX (PHASE SYNCHRONIZATION)
- EU ROHS COMPLIANT

APPLICATIONS

All Dual-Magnetron Sputtering Applications

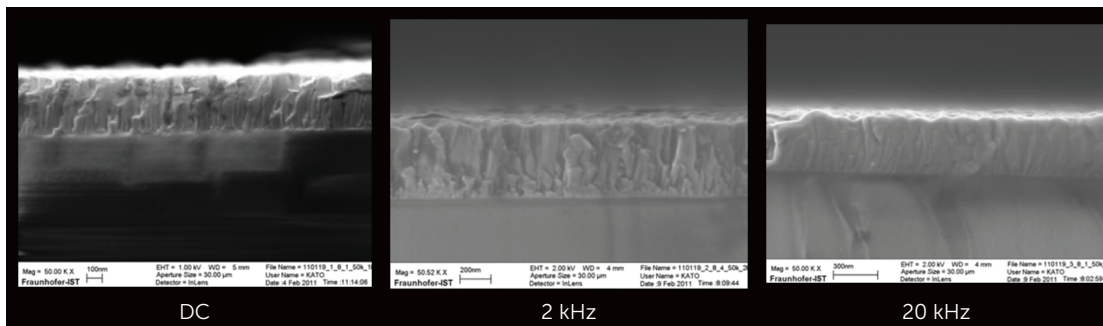


Optimized bipolar waveform for dual-magnetron sputtering applications

INCREASED FILM VALUE: REPEATABLE, CUSTOMIZABLE DEPOSITED FILMS

Create the ideal film density, uniformity, transmission, and resistivity for your application by selecting frequency (500 Hz to 50 kHz), regulation method (voltage, current, or power), and duty cycle (5 to 95%).

Fixed-frequency output stabilizes process conditions by eliminating resonant frequency changes, resulting in excellent repeatability. Low stored energy reduces arc-caused process contamination and film defects.



Precise tuning of film characteristics for advanced, narrow-margin applications

Create the ideal film density, uniformity, transmission, and resistivity for your application.

Target utilization of 85% or more

LOWER COST OWNERSHIP & INCREASED PRODUCTIVITY

The ability to individually control each magnetron increases target-erosion uniformity, while fixed-frequency output reduces arc energy and target nodule formation. These factors significantly reduce maintenance frequency and lengthen productive manufacturing time. They also decrease the cost of consumables by allowing target utilization of 85% or more.

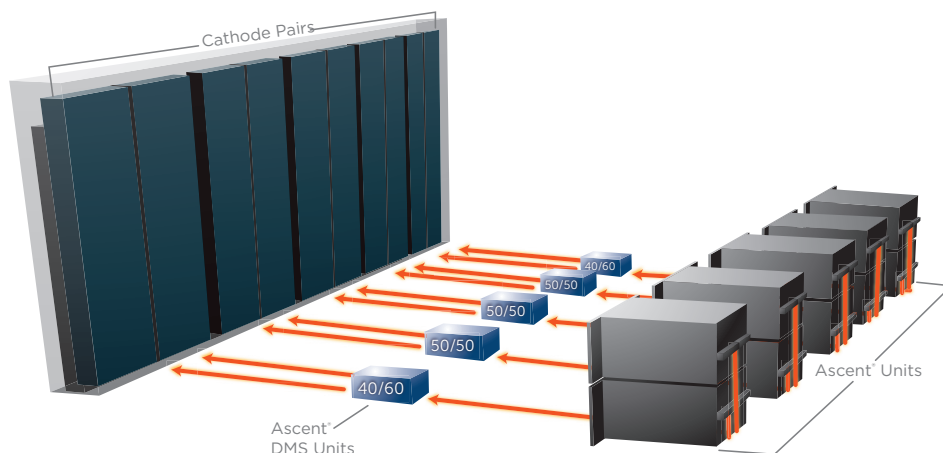
LOWER UPFRONT COSTS

With the ability to control power proportionally to each cathode, Ascent DMS configurations eliminate the need to use multiple power supply types, replacing separate AC, DC, and pulsed-DC units. This significantly reduces equipment, inventory, and training costs, and eases maintenance and support.

HIGHER POWER LEVELS WITH REDUCED ARC DAMAGE

Low arc energy and excellent arc management enable Ascent DMS configurations to achieve higher power levels without compromising film or process quality. While AC designs typically store 6 mJ/kW, Ascent DMS units store less than 1.0 mJ/kW, enabling successful deposition of even the most arc-prone materials, such as AZO, IGZO, IZO, ITO, and SiO₂.

INDEPENDENT POWER REGULATION TO EACH CATHODE



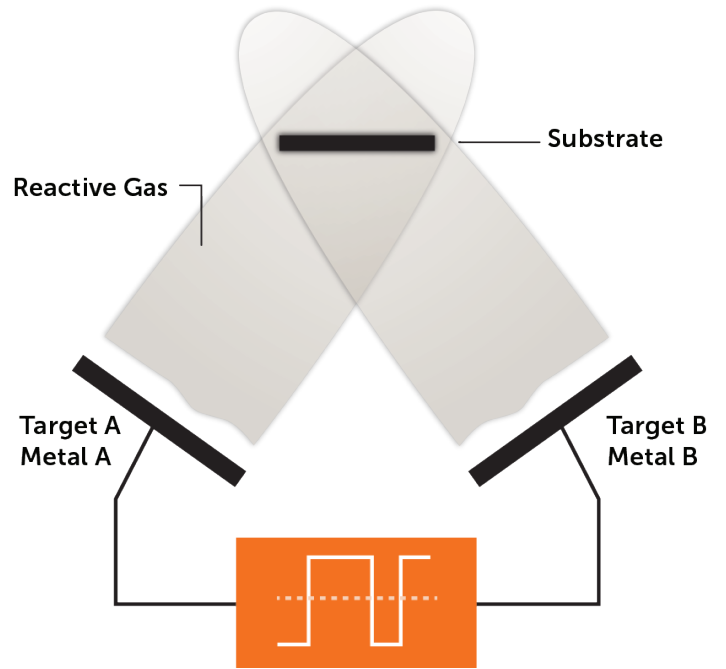
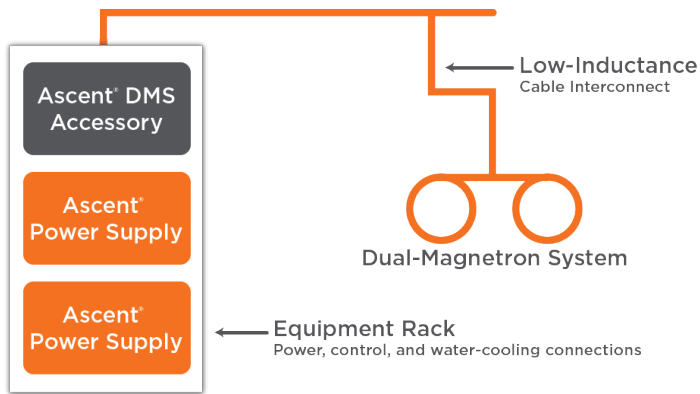
Ascent® DMS units control the sputter rate of each cathode individually. This enables more uniform target wear and sputtering in multi-cathode, single chamber systems, compared to AC supplies with fixed 50/50 duty cycles.

Modular and scalable, Ascent® DMS accessories enable customized installations from 30 to 180 kW, and provide DC and AC output from the same industry-standard 19" rack.



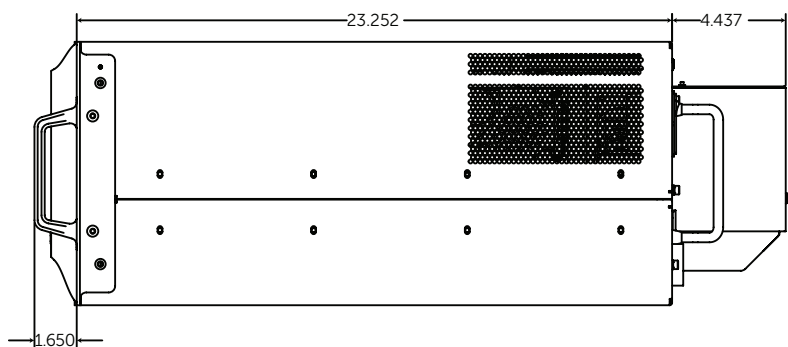
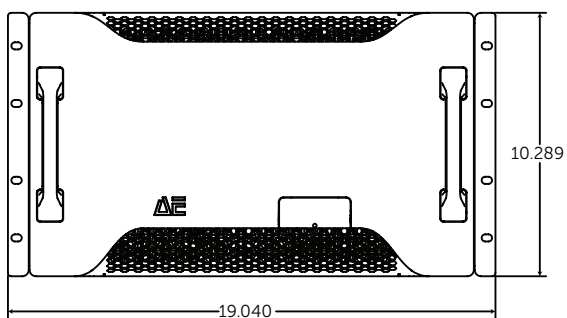
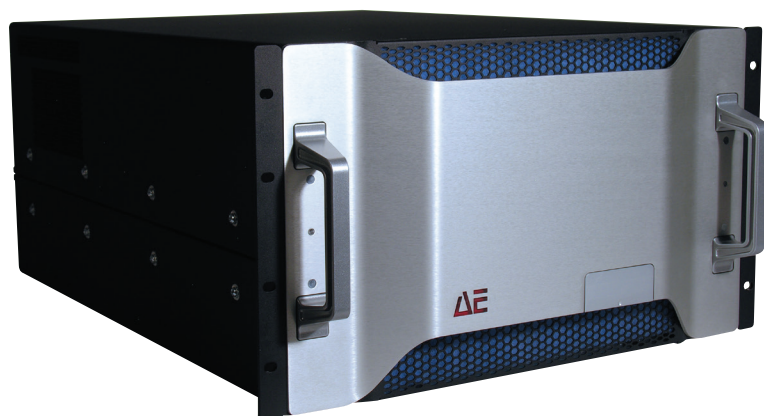
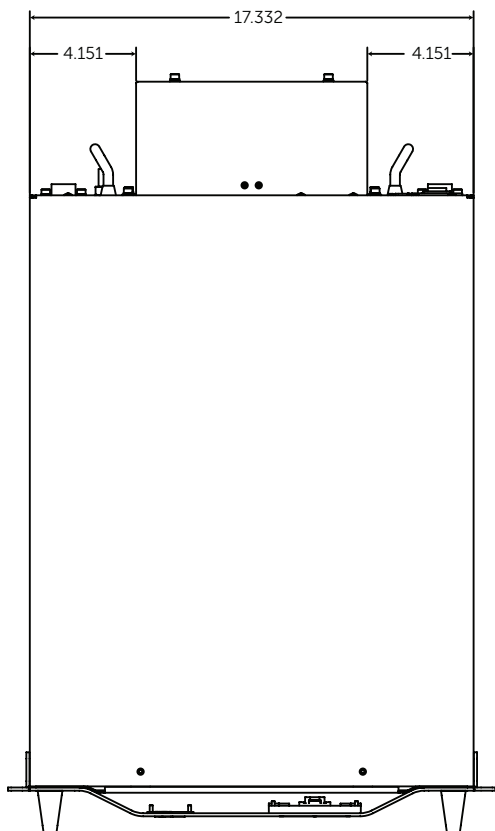
EASY SCALABILITY, INTEGRATION, AND SUPPORT

Ascent DMS units are modular and scalable, delivering 30 to 180 kW in increments of 30, 40, and 60 kW. CEX (phase synch) technology easily synchronizes multi-cathode systems, and allows cathodes to be placed closer together for better uniformity. This versatile series suits a mix of cathode types and allows co-sputtering of controlled mixtures of materials. Reduced configuration complexity also eases maintenance and support.



Co-sputtering: With the Ascent® DMS accessory, each magnetron receives the same power, eroding racetracks at the same rate.

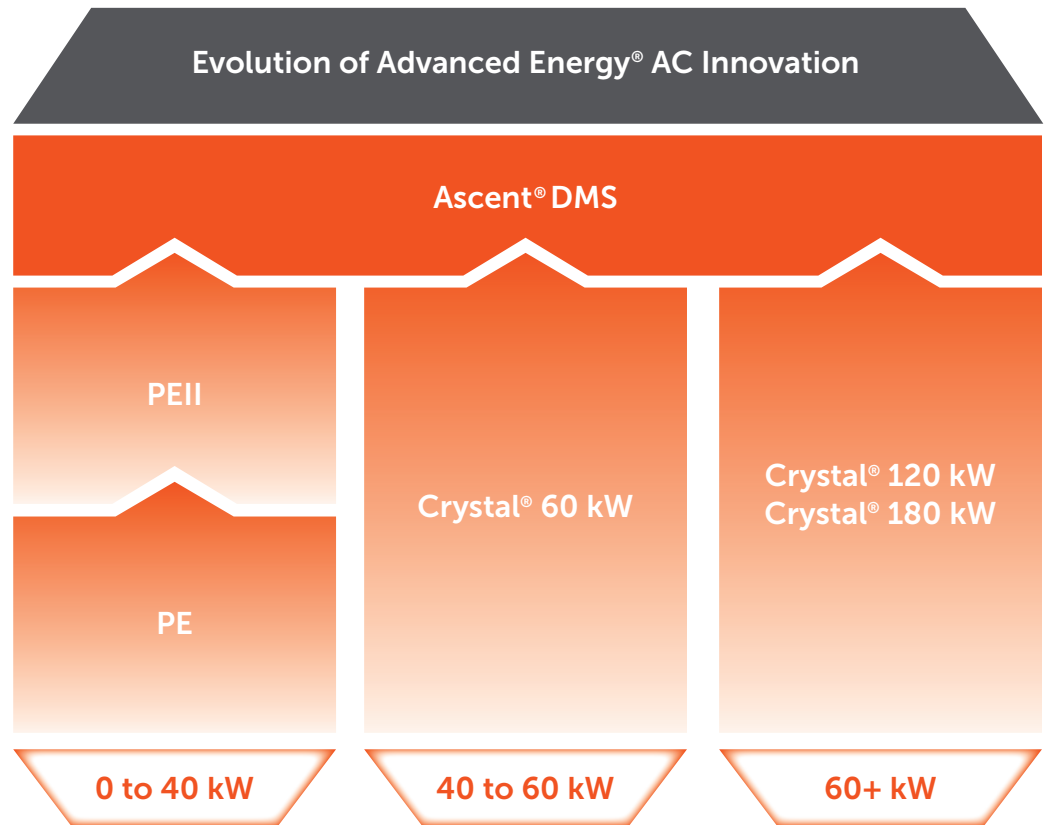
DIMENSIONAL DRAWING



SPECIFICATIONS

GENERAL SPECIFICATIONS	ASCENT® DMS 30 KW	ASCENT® DMS 40 KW	ASCENT® DMS 60 KW
Input Power¹	85 to 264 VAC, single		
Output Voltage	Up to 1000 V		
Output Current	Up to 150 A		
Min Output Current	1 A at 400 W		2 A at 600 W
I/O Communication	Ethernet, EtherCAT®, Profibus®, RS-232/485, analog, Virtual Front Panel (VFP) software, remote control panel, and passive-display front panel		
Weight	-61.5 kg (136 lb)		
Mounting	4.26 cm (19"), rack mountable, 6U height		
Cooling Air Temperature	40°C (104°F) max		
Cooling Water Temperature	35°C (95°F) max		
Compliance	EU RoHS, CE, NRTL, SEMI S2, SEMI F47		

¹ Ascent power supply input power: 400, 440, or 480 VAC ±10%, 50/60 Hz



AE World Headquarters
 1625 Sharp Point Drive
 Fort Collins, Colorado 80525

1 800 446 9167
+1 970 221 4670

sales.support@aei.com
advanced-energy.com

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